



# Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
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## Supplier Information

Company Name * ST Microelectronics	Company Unique ID	Unique ID Authority	Response Date * N/A	Response Document ID				
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *					
Authorized Representative * Giuseppe Vitali Palma	Title - Representative APM MD Champion	Phone - Representative * N/A	Email - Representative * N/A	Supplier Comments or URL for Additional Information				
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
	STPS60H100CT	H8DZ*Z15P02V	2010-06-30	A	Z45A	1,900	mg	Each
Alternate Recommendation	Package: TO220 AB NON ISOL			Alternate Item Comments	Ecopack 2/RoHS; BSA:271129			

## Manufacturing Process Information

Terminal Plating / Grid Array Material Matte Tin (Sn) - annealed	Terminal Base Alloy CU Alloy	J-STD-020 MSL Rating Not Applicable	Peak Process Body Temperature C	Max Time at Peak Temperature seconds	Number of Reflow Cycles Not Applicable
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Comments  
**DISCLAIMER: While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict "as is"**

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## RoHS Material Composition Declaration

Declaration Type \*

Simplified

**RoHS Directive 2002/95/EC** **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration \*

3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any

Supplier Acceptance \*

Accepted

**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version

EL-2006/690/EC

7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).

## Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Homogeneous Material Composition Declaration for Electronic Products

**SubItem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

**Line Functions:** +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem Name	Homogeneous Material	Weight	Unit of Measure	Level	Substance Category	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
											-	+	
H8DZ*Z15P02V	Silicon Die	16.512	mg	Supplier	Silicon die	Silicon	7440-21-3		16.067	mg			973,05
					die metallization	Aluminium(Al)	7429-90-5		0.304	mg			18,411
						Titanium (Ti)	7440-32-6		0.008	mg			484
						Nickel (Ni)	7440-02-0		0.11	mg			6,662
						(Gold (Au)	7440-57-5		0.023	mg			1,393
Leadframe	776.378	mg	supplier	alloy	Copper (Cu)	7440-50-8		775.369	mg			998,70	
					Iron (Fe)	7439-89-6		0.357	mg			460	
					Iron Phosphide (FeP)	26508-33-8		0.652	mg			840	
Leadframe coating	2.735	mg	supplier	coating	Nickel (Ni)	7440-02-0		2.418	mg			884,09	
					Phosphorus (P)	12185-10-3		0.317	mg			115,90	
Die Attach	11.512	mg	A	Lead/Lead Compound	Lead (Pb)	7439-92-1	7a. Lead	10.994	mg			955,00	
				supplier	glue	Silver (Ag)	7440-22-4		0.288	mg			25,017
						Tin (Sn)	7440-31-5		0.23	mg			19,979
Bonding wire	9.385	mg	Supplier	Bonding wire	Aluminium (Al)	7429-90-5		9.385	mg			1,000,0	
Encapsulation	1,086.49	mg	supplier	Moulding Compound	Silica, vitreous	60676-86-0		757.29	mg				697,00
					Epoxy Cresol Novolak	29690-82-2		206.435	mg			190,00	
					phenolic resin	9003-35-4		65.19	mg			60,000	
					metal hydroxide	Proprietary		54.325	mg			50,000	
					Carbon black	1333-86-4		3.259	mg			3,000	
Finishing	10.919	mg	supplier	connection coating	Tin (Sn)	7440-31-5		10.919	mg			1,000,0	